


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM8S001J3M3 STM8S001J3M3TR	C007*767VVVY	A	3068	27-03-2018
Amount	UoM	Unit type	ST ECOPACK Grade	
80.000	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SON	NAC	8	Gull Wing	
Comment	Package : 07 SO 08 .15 JEDEC 0016023			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	C007*767VVVY				5999999.0	999987.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	1.524	mg	supplier	die	Silicon (Si)	7440-21-3		1.442	mg	946194	18025
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	4593	88
				supplier	metallization	Copper (Cu)	7440-50-8		0.024	mg	15748	300
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.003	mg	1969	38
				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	2625	50
				supplier	Passivation	Silicon Nitride	12033-89-5		0.006	mg	3937	75
				supplier	Passivation	Silicon Oxide	7631-86-9		0.038	mg	24934	475
Lead-frame	M-011 Other inorganic materials	30.429	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.420	mg	966854	367756
				supplier	alloy	Iron (Fe)	7439-89-6		0.708	mg	23276	8853
				supplier	alloy	Zinc (Zn)	7440-66-6		0.036	mg	1191	453
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.025	mg	833	317
				supplier	coating	Nickel (Ni)	7440-02-0		0.114	mg	3746	1425
				supplier	coating	Palladium (Pd)	7440-05-3		0.007	mg	240	91
				supplier	coating	Gold (Au)	7440-57-5		0.114	mg	3738	1422
Die Attach	M-011 Other inorganic materials	0.105	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		0.004	mg	121	46
				supplier	glue or soft solder	Silver (Ag)	7440-22-4		0.003	mg	32768	43
				supplier	glue or soft solder	acrylate	Proprietary		0.003	mg	32768	43
				supplier	glue or soft solder	Methacrylate	Proprietary		0.093	mg	887740	1169
Wires	M-011 Other inorganic materials	0.062	mg	supplier	glue or soft solder	acrylate	Proprietary		0.005	mg	46723	62
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.062	mg	1000000	776
				supplier	Moulding Compound	Epoxy Resin	Proprietary		3.178	mg	66370	39720
Encapsulation	M-011 Other inorganic materials	47.877	mg	supplier	Moulding Compound	Phenol Resin	Proprietary		2.118	mg	44247	26480
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		42.200	mg	881419	527500
				supplier	Moulding Compound	Carbon-black	1333-86-4		0.212	mg	4425	2648
				supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.169	mg	3540	2118
Finishing	M-011 Other inorganic materials	0.001	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.001	mg	914840	14
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	29660	0
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	27750	0
				supplier	connections coating	Silver (Ag)	7440-22-4		0.000	mg	27750	0